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FAIRCHILD SEMICONDUCTOR™

May 2002
Revised May 2002

74LVT322373 • 74LVTH322373
Low Voltage 32-Bit Transparent Latch with 3-STATE Outputs and 25Ω Series Resistors in the Outputs

General Description

The LVT322373 and LVTH322373 contain thirty-two non-inverting latches with 3-STATE outputs and are intended for bus oriented applications. The device is byte controlled. The flip-flops appear transparent to the data when the Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable ($\overline{OE}$) is LOW. When $\overline{OE}$ is HIGH, the outputs are in a high impedance state.

The LVTH322373 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These latches are designed for low voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT322373 and LVTH322373 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH322373), also available without bushold feature (74LVT322373)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs include equivalent series resistance of 25Ω to make external termination resistors unnecessary and reduce overshoot and undershoot
- ESD performance:
  Human-body model > 2000V
  Machine model > 200V
  Charged-device model > 1000V
- Packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

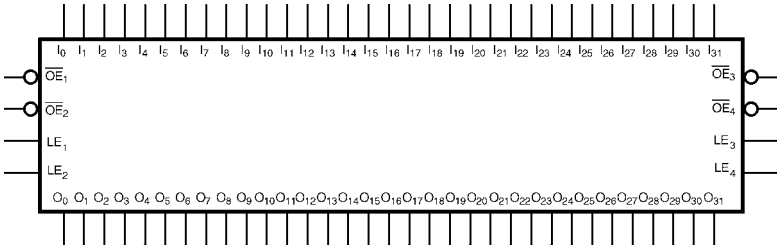
Ordering Code:

Order Number	Package Number	Package Description
74LVT322373G (Note 1) (Note 2)	BGA96A (Preliminary)	96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74LVTH322373G (Note 1) (Note 2)	BGA96A	96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide

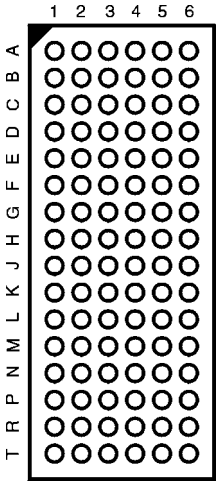
Note 1: Ordering Code "G" indicates Trays.

Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



(Top Thru View)

Pin Descriptions

Pin Names	Description
$\overline{OE}_n$	Output Enable Input (Active LOW)
LE_n	Latch Enable Input
I_0–I_{31}	Inputs
O_0–O_{31}	3-STATE Outputs

FBGA Pin Assignments

	1	2	3	4	5	6
A	O_1	O_0	$\overline{OE}_1$	LE_1	I_0	I_1
B	O_3	O_2	GND	GND	I_2	I_3
C	O_5	O_4	V_{CC1}	V_{CC1}	I_4	I_5
D	O_7	O_6	GND	GND	I_6	I_7
E	O_9	O_8	GND	GND	I_8	I_9
F	O_{11}	O_{10}	V_{CC1}	V_{CC1}	I_{10}	I_{11}
G	O_{13}	O_{12}	GND	GND	I_{12}	I_{13}
H	O_{14}	O_{15}	$\overline{OE}_2$	LE_2	I_{15}	I_{14}
J	O_{17}	O_{16}	$\overline{OE}_3$	LE_3	I_{16}	I_{17}
K	O_{19}	O_{18}	GND	GND	I_{18}	I_{19}
L	O_{21}	O_{20}	V_{CC2}	V_{CC2}	I_{20}	I_{21}
M	O_{23}	O_{22}	GND	GND	I_{22}	I_{23}
N	O_{25}	O_{24}	GND	GND	I_{24}	I_{25}
P	O_{27}	O_{26}	V_{CC2}	V_{CC2}	I_{26}	I_{27}
R	O_{29}	O_{28}	GND	GND	I_{28}	I_{29}
T	O_{30}	O_{31}	$\overline{OE}_4$	LE_4	I_{31}	I_{30}

Truth Table

Inputs			Outputs
LE_1	$\overline{OE}_1$	I_0–I_7	O_0–O_7
X	H	X	Z
H	L	L	L
H	L	H	H
L	L	X	O_0

Inputs			Outputs
LE_2	$\overline{OE}_2$	I_8–I_{15}	O_8–O_{15}
X	H	X	Z
H	L	L	L
H	L	H	H
L	L	X	O_0

Inputs			Outputs
LE_3	$\overline{OE}_3$	I_{16}–I_{23}	O_{16}–O_{23}
X	H	X	Z
H	L	L	L
H	L	H	H
L	L	X	O_0

Inputs			Outputs
LE_4	$\overline{OE}_4$	I_{24}–I_{31}	O_{24}–O_{31}
X	H	X	Z
H	L	L	L
H	L	H	H
L	L	X	O_0

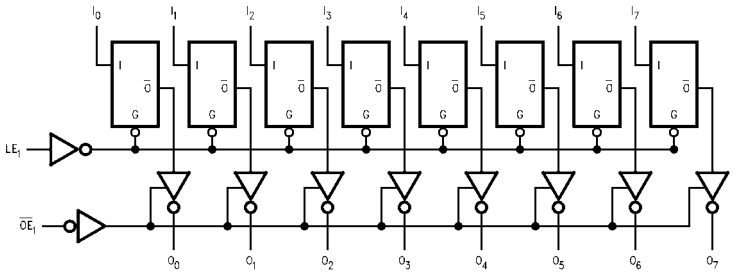
H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial Z = HIGH Impedance O_o = Previous O_o prior to HIGH-to-LOW transition of LE

Functional Description

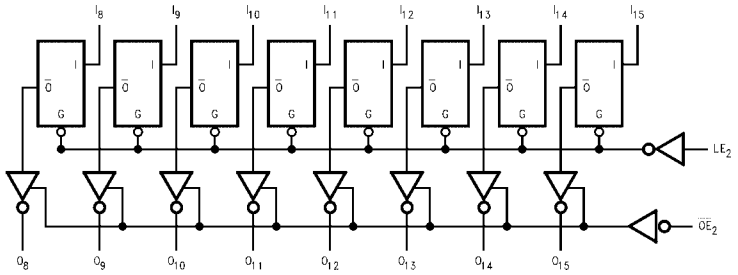
The LVT322373 and LVTH322373 contain thirty-two D-type latches with 3-STATE standard outputs. The device is byte controlled with each byte functioning identically, but independent of the other. Control pins can be shorted together to obtain full 32-bit operation. The following description applies to each byte. When the Latch Enable (LE_n) input is HIGH, data on the D_n enters the latches. In this condition the latches are transparent, i.e, a latch output will change states each time its D input changes. When LE_n is LOW, the latches store information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE_n. The 3-STATE standard outputs are controlled by the Output Enable ($\overline{OE}_n$) input. When $\overline{OE}_n$ is LOW, the standard outputs are in the 2-state mode. When $\overline{OE}_n$ is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Diagrams

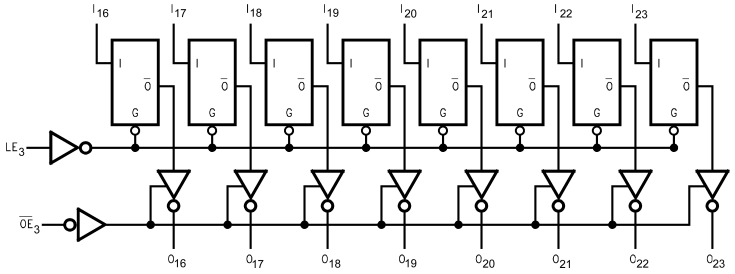
Byte 1 (0:7)



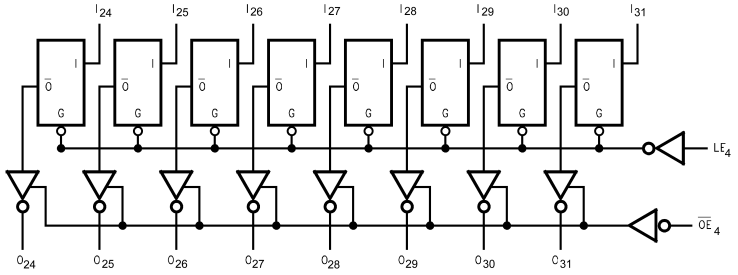
Byte 2 (8:15)



Byte 3 (16:23)



Byte 4 (24:31)



V_{CC1} is associated with Bytes 1 and 2.

V_{CC2} is associated with Bytes 3 and 4.

Note: Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 3)

Symbol	Parameter	Value	Conditions	Units
V_{CC}	Supply Voltage	−0.5 to +4.6		V
V_I	DC Input Voltage	−0.5 to +7.0		V
V_O	DC Output Voltage	−0.5 to +7.0	Output in 3-STATE	V
		−0.5 to +7.0	Output in HIGH or LOW State (Note 4)	
I_{IK}	DC Input Diode Current	−50	V_I < GND	mA
I_{OK}	DC Output Diode Current	−50	V_O < GND	mA
I_O	DC Output Current	64	$V_O > V_{CC}$ Output at HIGH State	mA
		128	$V_O > V_{CC}$ Output at LOW State	
I_{CC}	DC Supply Current per Supply Pin	±64		mA
I_{GND}	DC Ground Current per Ground Pin	±128		mA
T_{STG}	Storage Temperature	−65 to +150		°C

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage	2.7	3.6	V
V_I	Input Voltage	0	5.5	V
I_{OH}	HIGH Level Output Current		−12	mA
I_{OL}	LOW Level Output Current		12	mA
T_A	Free-Air Operating Temperature	−40	85	°C
$\Delta t/\Delta V$	Input Edge Rate, V_{IN} = 0.8V to 2.0V, V_{CC} = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter		V_{CC} (V)	T_A = −40°C to +85°C Min	T_A = −40°C to +85°C Max	Units	Conditions
V_{IK}	Input Clamp Diode Voltage		2.7		−1.2	V	I_I = −18 mA
V_{IH}	Input HIGH Voltage		2.7 - 3.6	2.0		V	$V_O \le 0.1V$ or
V_{IL}	Input LOW Voltage		2.7 - 3.6		0.8	V	$V_O \ge V_{CC} - 0.1V$
V_{OH}	Output HIGH Voltage		2.7 - 3.6	V_{CC} − 0.2		V	I_{OH} = −100 µA
			3.0	2.0			I_{OH} = −12 mA
V_{OL}	Output LOW Voltage		2.7		0.2	V	I_{OL} = 100 µA
			3.0		0.8		I_{OL} = 12 mA
$I_{I(HOLD)}$	Bushold Input Minimum Drive		3.0	75		µA	V_I = 0.8V
				−75			V_I = 2.0V
$I_{I(OD)}$	Bushold Input Over-Drive Current to Change State		3.0	500		µA	(Note 5)
				−500			(Note 6)
I_I	Input Current		3.6		10	µA	V_I = 5.5V
		Control Pins	3.6		±1		V_I = 0V or V_{CC}
		Data Pins	3.6		−5		V_I = 0V
					1		V_I = V_{CC}
I_{OFF}	Power Off Leakage Current		0		±100	µA	$0V \le V_I$ or $V_O \le 5.5V$
$I_{PU/PD}$	Power up/down 3-STATE Output Current		0 - 1.5V		±100	µA	V_O = 0.5V to 3.0V V_I = GND or V_{CC}
I_{OZL}	3-STATE Output Leakage Current		3.6		−5	µA	V_O = 0.5V
I_{OZH}	3-STATE Output Leakage Current		3.6		5	µA	V_O = 3.0V
I_{OZH+}	3-STATE Output Leakage Current		3.6		10	µA	$V_{CC} < V_O \le 5.5V$
I_{CCH}	Power Supply Current	(V_{CC1} or V_{CC2})	3.6		0.19	mA	Outputs HIGH
I_{CCL}	Power Supply Current	(V_{CC1} or V_{CC2})	3.6		5	mA	Outputs LOW
I_{CCZ}	Power Supply Current	(V_{CC1} or V_{CC2})	3.6		0.19	mA	Outputs Disabled

DC Electrical Characteristics (Continued)

Symbol	Parameter	V_{CC} (V)	$T_A = -40°C$ to $+85°C$		Units	Conditions
			Min	Max		
I_{CCZ}+	Power Supply Current (V_{CC1} or V_{CC2})	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$, Outputs Disabled
ΔI_{CC}	Increase in Power Supply Current (V_{CC1} or V_{CC2}) (Note 7)	3.6		0.2	mA	One Input at $V_{CC} - 0.6V$ Other Inputs at V_{CC} or GND

Note 5: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 6: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 7: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 8)

Symbol	Parameter	V_{CC} (V)	$T_A = 25°C$			Units	Conditions $C_L = 50$ pF, $R_L = 500\Omega$
			Min	Typ	Max		
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	3.3		0.8		V	(Note 9)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	3.3		−0.8		V	(Note 9)

Note 8: Characterized in SSOP package. Guaranteed parameter, but not tested.

Note 9: Max number of outputs defined as (n). n−1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

Symbol	Parameter	$T_A = -40°C$ to $+85°C$, $C_L = 50$pF, $R_L = 500\Omega$				Units
		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.7V$		
		Min	Max	Min	Max	
t_{PHL}	Propagation Delay	1.3	4.8	1.3	5.3	ns
t_{PLH}	D_n to O_n	1.4	4.8	1.4	5.1	
t_{PHL}	Propagation Delay	1.7	5.0	1.7	5.1	ns
t_{PLH}	LE to O_n	1.4	5.1	1.4	5.8	
t_{PZL}	Output Enable Time	1.6	5.0	1.6	6.0	ns
t_{PZH}		1.0	5.4	1.0	6.6	
t_{PLZ}	Output Disable Time	1.6	5.1	1.6	5.0	ns
t_{PHZ}		1.8	5.4	1.8	5.7	
t_S	Setup Time, D_n to LE	1.0		0.8		ns
t_H	Hold Time, D_n to LE	1.0		1.1		ns
t_W	LE Pulse Width	3.0		3.0		ns
t_{OSHL}	Output to Output Skew (Note 10)		1.0		1.0	ns
t_{OSLH}			1.0		1.0	

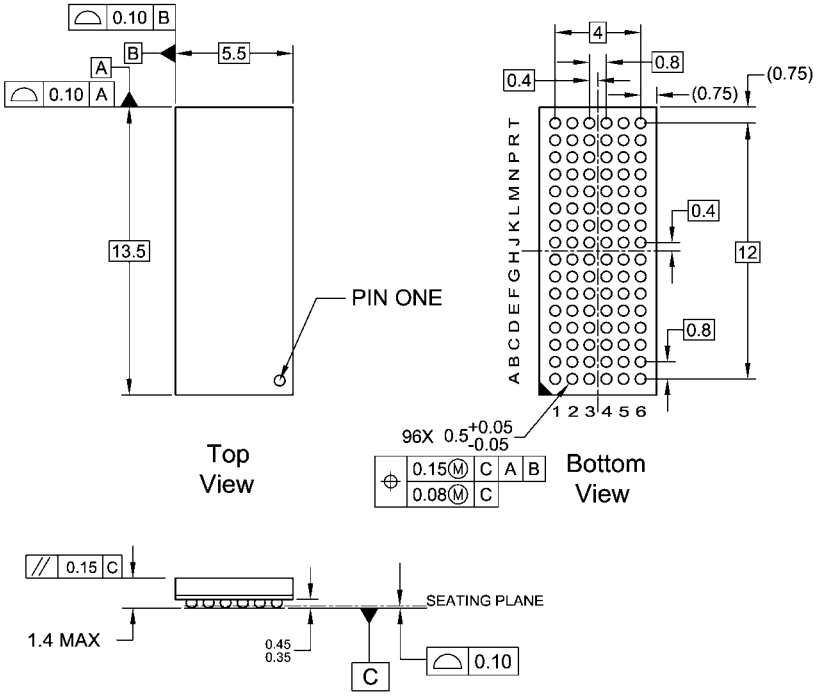
Note 10: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Capacitance (Note 11)

Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	V_{CC} = Open, $V_I = 0V$ or V_{CC}	4	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_O = 0V$ or V_{CC}	8	pF

Note 11: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted



NOTES:

A. THIS PACKAGE CONFORMS TO JEDEC M0-205
B. ALL DIMENSIONS IN MILLIMETERS
C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA96ArevE

96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
Package Number BGA96A
Preliminary

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